H.14		
	Application No.	Applicant(s)
AL C. C. Allerman 1994	09/255,856	IWASAKI ET AL.
Notice of Allowability	Examiner	Art Unit
	Stephen W. Smoot	2813
The MAILING DATE of this communication appears All claims being allowable, PROSECUTION ON THE MERITS IS nerewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT R of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this apply or other appropriate communication IGHTS. This application is subject to	plication. If not included n will be mailed in due course. THIS
1. X This communication is responsive to applicant's RCE filed on 23 June 2005.		
2. The allowed claim(s) is/are <u>1-3,5,6,12-15,32,38 and 39</u> .		
3. The drawings filed on 23 February 1999 are accepted by the Examiner.		
 4. Acknowledgment is made of a claim for foreign priority unas a) All b) Some* c) None of the: Certified copies of the priority documents have Certified copies of the priority documents have Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONA THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 	e been received. e been received in Application No cuments have been received in this of this communication to file a reply	national stage application from the
5. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.		
 6. CORRECTED DRAWINGS (as "replacement sheets") must be submitted. (a) including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d). 7. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL. 		
 Attachment(s) 1. ☐ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☒ Information Disclosure Statements (PTO-1449 or PTO/SB/I) Paper No./Mail Date 6-23-05; 7-20-05 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material 	6. Interview Summary Paper No./Mail Da 08), 7. Examiner's Amendr	te ment/Comment ent of Reasons for Allowance
Stephen	n W. Smoot	Stephen W. Smoot Patent Examiner Art Unit 2813

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DETAILED ACTION

This Office action is in response to applicant's RCE filed on 23 June 2005.

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's amendment filed on 23 June 2005 has been entered. Also, applicant's IDSs filed on 23 June 2005 and 20 July 2005 have been considered.

Allowable Subject Matter

- 2. Claims 1-3, 5-6, 12-15, 32, 38-39 are allowed.
- 3. The following is an examiner's statement of reasons for allowance:

Claims 1-3, 32 are allowed because the prior art of record does not teach or suggest, in combination with the other claim limitations, a semiconductor device with a multilayered structure that includes a copper film interconnect that has at least two copper films, wherein the copper film interconnect is in contact with a neighboring film that includes a ruthenium film;

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- Claims 5-6, 39 are allowed because the prior art of record does not teach or suggest, in combination with the other claim limitations, a semiconductor device that includes a copper film interconnect formed on one primary surface of a semiconductor substrate, a neighboring film in contact with the copper film interconnect, and a plug formed in contact with the neighboring film, wherein the plug is formed of ruthenium as the primary constituent element; and
- Claims 38, 12-15 are allowed because the prior art of record does not teach or suggest, in combination with the other claim limitations, a semiconductor device having a layered interconnection structure that includes a platinum film formed overlying a surface of a semiconductor substrate, a diffusion barrier layer, and a neighboring film sandwiched between the platinum film and the diffusion barrier layer, wherein the neighboring film includes a material selected from a group consisting of rhodium, ruthenium, iridium, and osmium.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Stephen W. Smoot whose telephone number is 571-272-1698. The examiner can normally be reached on M-F (8:00 am to 4:30 pm).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on 571-272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8000.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).